Gas Discharge Tubes (GDT)

Description

RLIL&N

Gas discharge tubes (GDT) use noble gasses enclosed in ceramic tubes to provide an alternate circuit path for voltage spikes. The ceramic envelope and with nickel connectors allow for high loads. SMD5050 Gas Discharge Tubes (GDT) series has a surge rating of 5kA, 8/20µs.Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

SMD5050 Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.

Features

- I Excellent response to fast rising transients
- Stable breakdown voltage I
- I GHz working frequency
- 8/20µs Impulse current capability:5KA I
- Surface Mount package I
- Non-Radioactive I
- Ultra Low capacitance (<0.8pF) I
- Size: 4.2mm*5mm*5mm I

Part Number Code

M

Surface Mount Package

S

Storage and operational temperature: -40~+125°C I

D

5

5

0

0

Product Series

Size: 4.2mm*5mm*5mm

8/20µs Impulse Current A: 5KA

SMD5050 Series

Electrical symbol

Agency	Standards	Certificate No.
A 1°	UL497B	E465335
TÛVRheinland	EN 61643-311 IEC 61643-311	J50569381

Applications

- CATV equipment L
- L Antennas
- L RS 485
- I **Telecom Base Station**
- Power Supply AC Main L
- EV power Charging L
- L Inverter/Variable

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- **Frequency Drivers** L (VFDs)
- L IEEE 802.3 compliant Ethernet interfaces

- Broad Band equipment Т
- xDSL, ADSL, ADSL2, Т VDSL, and VDSL2
- L **Medical Electronics**
- Test Equipment Т

Ν

- **General Telecom** Equipment
- **Renewable Energy** Т

DC Spark-over Voltage DC Spark-over Voltage Tolerance N: ±30%

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SMD5050 Series

Electrical Characteristics

	DC Spark-over	Impulse Spark-over Voltage		Resistance		Glow Voltage @10mA	-	Life Ratings 4)			
					Capacitance @1MHz			Cur	Discharge rent	Alternating Discharge Current	Impulse Life @10/1000µS
Part Number	Voltage ^{1) 2)} @100V/S	100V/µS [~]	1KV/µS	5				@8/20µS		@50Hz 1S	Closecope
		Max	Max	Min	Max	Typical	Typical	±5 times	1 time	10 times	300 times
	v	v	v	GΩ	pF	v	v	KA	KA	Α	А
SMD5050-075NA	75±30%	500	600	1	0.8	60	10	5	10	5	100
SMD5050-090NA	90±30%	500	600	1	0.8	60	10	5	10	5	100
SMD5050-150NA	150±30%	500	600	1	0.8	60	10	5	10	5	100
SMD5050-200NA	200±30%	600	700	1	0.8	60	10	5	10	5	100
SMD5050-230NA	230±30%	600	700	1	0.8	60	10	5	10	5	100
SMD5050-300NA	300±30%	750	850	1	0.8	60	10	5	10	5	100
SMD5050-350NA	350±30%	800	900	1	0.8	60	10	5	10	5	100
SMD5050-400NA	400±30%	800	900	1	0.8	135	15	5	10	5	100
SMD5050-420NA	420±30%	850	950	1	0.8	135	15	5	10	5	100
SMD5050-470NA	470±30%	850	950	1	0.8	135	15	5	10	5	100
SMD5050-600NA	600±30%	900	1000	1	0.8	135	15	5	10	5	100
SMD5050-800NA	800±30%	1200	1400	1	0.8	135	15	5	10	5	100
Glow to Arc transitio	n Current				<0.5A						
Weight					~0.42g						
Operation temperate	ure				40~+12	5°C					
Recommended storage ⁵⁾											
- Temperature				+5~+35°	С						
- Humidity				45~+80%	. 45~+80%						
- Period				,							
	Climatic category (IEC 60068-1)				1						
Marking				Without							
	Surface treatment					plated					
Moisture sensitivity level 6				1							

¹⁾ At delivery AQL 0.65 level II, DIN ISO 2859.

²⁾ In ionized mode.

³⁾ Insulation Resistance Measuring Voltage: nominal voltage 75~150V at DC 50V, others at DC 100V.

⁴⁾ Tests according to ITU-T K.12 and UL 497B.

⁵⁾ Specified in terms of corrosion against tin plating.

⁶⁾ Tests according to JEDEC J-STD-020.

Terms and current waveforms in accordance with ITU-T K. 12, IEC61643-21 and IEC 61643-311.



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Certifications table

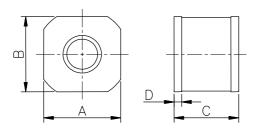
Dent Neurolean	9 1°	TÜVRheinland
Part Number	UL497B	EN 61643-311 IEC 61643-311
SMD5050-075NA	•	
SMD5050-090NA	•	-
SMD5050-150NA	•	
SMD5050-200NA	•	
SMD5050-230NA	•	
SMD5050-300NA	•	
SMD5050-350NA	•	
SMD5050-400NA	•	
SMD5050-420NA		
SMD5050-470NA	•	
SMD5050-600NA	•	•
SMD5050-800NA		

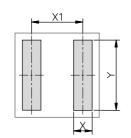
Notes:

1. • indicates that the product has passed the certification.

2. -- indicates that the product is not certified.

Dimensions





Recommended Soldering Pad Layout

Symbol	Millimeters	Inches		
Α	5.0±0.2	0.197±0.008		
В	5.0±0.2	0.197±0.008		
с	4.2±0.3	0.165±0.012		
D	0.5±0.1	0.020±0.004		
x	1.2	0.047		
X1	4.0	0.165		
Y	5.5	0.217		

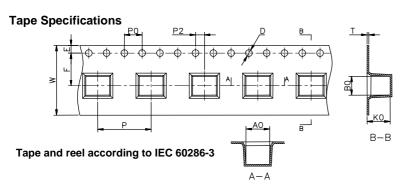


Gas Discharge Tubes (GDT)

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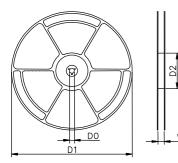
Inches

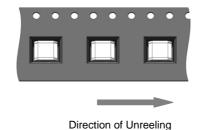
Packaging Information



W1

Reel Specifications





w	16±0.3	0.630±0.012		
A0	5.3±0.1	0.209±0.004		
B0	4.3±0.1	0.17±0.004		
К0	5.2±0.1	0.205±0.004		
Р	12±0.1	0.472±0.004		
F	7.5±0.1	0.295±0.004		
E	1.75±0.1	0.069±0.004		
D	1.5+0.1/-0.0	0.059+0.004/-0.0		
P0	4±0.1	0.157±0.004		
P2	2±0.1	0.079±0.004		
т	0.4±0.1	0.016±0.004		
D0	13.3±0.15	0.524±0.006		
D1	330±2	12.992±0.079		
D2	100+1/-2 3.937+0.039/-0.079			
W1	W1 16.5±0.4 0.65±0.016			

Millimeters

Symbol

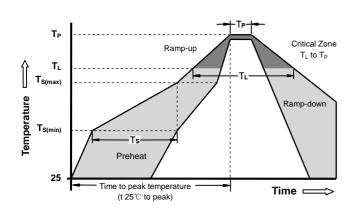
	Reel	Inner Box	Carton
Size	330×17mm	340×333×70mm	375×353×380mm
Quantity	MPQ/MOQ: 1 reel=1,000pcs	1 Inner Box=3 reels=3,000pcs	1Carton=5 Inner boxes=15,000pcs
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Gas Discharge Tubes (GDT)

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Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Cond	ition	Pb - Free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Preheat	-Temperature Max (T _{s(max)})	200°C	
	- Time (min to max) (t _s)	60 -180 Seconds	
Average ram to peak	p up rate (Liquids Temp T _L)	3°C/second max	
T _{S(max)} to TL -	Ramp-up Rate	5°C/second max	
Reflow	 Temperature (T_L) (Liquids) 	217°C	
	- Time (min to max) (t _s)	60 -150 Seconds	
Peak Temper	ature (T _P)	260 +0/-5°C	
Time within 5 Temperature	i°C of actual peak (t _p)	10 - 30 Seconds	

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

Terms and definitions

NO.	ltem	Definitions	
1	Gas discharge tube(GDT)	A gap, or several gaps, in an enclosed discharge medium, other than air at atmospheric pressure, designed to protect apparatus or personnel, or both, from high transient voltages. Also referred to as "gas tube surge arrester".	
2	DC Spark-over Voltage	The voltage at which the gas discharge tube sparks over with slowly increasing d.c. voltage.	
3	Impulse Spark-over Voltage	The highest voltage which appears across the terminals of a gas discharge tube in the period between the application of an impulse of given wave-shape and the time when current begins to flow.	
5	Arc voltage	Voltage drop across the GDT during arc current flow.	
6	Glow voltage	Peak value of voltage drop across the GDT when a glow current is flowing.	
7	Impulse discharge current 8/20µs	Current impulse with a nominal virtual front time of 8 μs and a nominal time to half-value of 20 $\mu s.$	
8	Alternating Discharge Current	The rms value of an approximately sinusoidal alternating current passing through the gas discharge tube.	
9	Insulation Resistance	Insulation resistance shall be measured from each terminal to every other terminal of the GDT. The test is performed with DC50V when normal spark-over Voltage 70~150V, others with DC100V.	
10	Capacitance	The capacitance shall be measured once at 1 MHz between all terminals unless otherwise specified.	

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Cautions and warnings

- I Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- I Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- I Surge arresters must be handled with care and must not be dropped.
- I Do not continue to use damaged surge arresters.
- I The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- I SMD surge arresters should be soldered within 24 month after shipment.